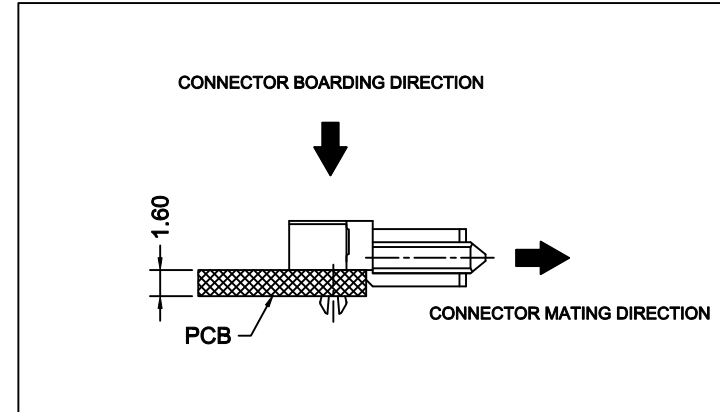


RECOMMENDED PCB LAYOUT
PCB THICKNESS : 1.6mm

NOTES:

- MATERIAL
 - HOUSING : HIGH TEMP THERMOPLASTIC UL94V-0(COLOR: BLACK)
 - TERMINAL : COPPER ALLOY
 - HOLD DOWN : COPPER ALLOY
- FINISH
 - TERMINAL : Au PLATING (CONTACT POINT) OVER 50u" NICKEL
 - SOLDER TAIL : 50u" min MATT TIN OVER 50u" NICKEL
 - HOLD DOWN : 50u" min MATT TIN OVER 50u" NICKEL
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260° FOR 10 SEC. IN REFLOW SOLDER APPLICATION WITH 1.6MM MINIMUM CIRCUIT BOARD.
- PRODUCT SPEC:GS-12-494
PACKING SPEC:GS-14-1283
- PRODUCT NUMBERING:
10105229 - X 0 0 X LF

1: TRAY PACKING
0: 5U" GOLD PLATING



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mat'l. code				tolerances unless otherwise specified				CUSTOMER COPY		FCI www.fciconnect.com	
ltr	ecn no	dr	date	linear	.X ± 0.38	projection	title				
A	T09-1141	S.LIN	11/02/09'	angles	.XX ± 0.25		MICRO S-ATA RECEP R/A, SMT TYPE				
					.XXX ± 0.15	MM	product family		SATA		
				dr	STERLING LIN 11/02/09'	scale	size		dwg no		code
				engr	STERLING LIN 11/02/09'	NA	A4		10105229		TWN
				chr	GARY HSIEH 11/02/09'						sheet
				appd	JOSEPH HSIA 11/02/09'						1 of 1
sheet index	revision sheet	A	1								